ABSTRACT

There is provided a semiconductor device capable of capable of improving element performance and reliability. A semiconductor device includes a lower conductive pattern disposed on a substrate, an upper conductive pattern disposed on the lower conductive pattern, and a first plug pattern disposed between the lower conductive pattern and the upper conductive pattern and connected to the lower conductive pattern and the upper conductive pattern. The first plug pattern includes a first barrier pattern that defines a first plug recess and a first plug metal pattern that fills the first plug recess, and the first plug metal pattern includes a first molybdenum pattern and a first tungsten pattern disposed on the first molybdenum pattern.

FIG. 2